



# SGMOP07

## 3MHz, Low Noise, High Voltage, Precision Operational Amplifier

### GENERAL DESCRIPTION

The SGMOP07 is a single, low noise and low offset voltage operational amplifier. It is optimized for high voltage operation from 3.6V to 36V single supply or  $\pm 1.8V$  to  $\pm 18V$  dual supplies, while consuming only 0.9mA quiescent current.

The SGMOP07 is well suited in low noise systems. It exhibits a high gain-bandwidth product of 3MHz and a slew rate of 4V/ $\mu s$ . The output swing is rail-to-rail with heavy loads. These specifications make the operational amplifier appropriate for various applications.

The SGMOP07 is available in a Green SOIC-8 package. It is specified over the extended  $-40^{\circ}C$  to  $+125^{\circ}C$  temperature range.

### FEATURES

- **Low Noise:**  $8.5nV/\sqrt{Hz}$  at 1kHz
- **Low Bias Current:**  $\pm 1nA$  (TYP)
- **High Open-Loop Gain:** 120dB at  $V_S = \pm 15V$
- **High PSRR:** 146dB
- **High Gain-Bandwidth Product:** 3MHz
- **Settling Time to 0.1% with 1V Step:** 0.5 $\mu s$
- **Overload Recovery Time:** 10 $\mu s$
- **Rail-to-Rail Output**
- **Support Single or Dual Power Supplies:**  
3.6V to 36V or  $\pm 1.8V$  to  $\pm 18V$
- **Input Common Mode Voltage Range:**  
 $(-V_S) + 1.5V$  to  $(+V_S) - 2V$
- **Low Quiescent Current:** 0.9mA (TYP)
- **$-40^{\circ}C$  to  $+125^{\circ}C$  Operating Temperature Range**
- **Available in a Green SOIC-8 Package**

### APPLICATIONS

Sensors  
Audio  
Active Filters  
A/D Converters  
Communications  
Test Equipment  
Cellular and Cordless Phones  
Laptops and PDAs  
Photodiode Amplification

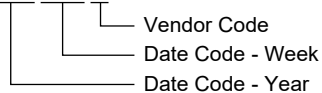
## PACKAGE/ORDERING INFORMATION

MODEL	PACKAGE DESCRIPTION	SPECIFIED TEMPERATURE RANGE	ORDERING NUMBER	PACKAGE MARKING	PACKING OPTION
SGMOP07	SOIC-8	-40°C to +125°C	SGMOP07XS8G/TR	SGM OP07XS8 XXXXX	Tape and Reel, 2500

## MARKING INFORMATION

NOTE: XXXXX = Date Code and Vendor Code.

XXXXX



Green (RoHS & HSF): SG Micro Corp defines "Green" to mean Pb-Free (RoHS compatible) and free of halogen substances. If you have additional comments or questions, please contact your SGMICRO representative directly.

## ABSOLUTE MAXIMUM RATINGS

Supply Voltage, $+V_S$ to $-V_S$	40V
Input Common Mode Voltage Range	$(-V_S) - 0.3V$ to $(+V_S) + 0.3V$
Junction Temperature	+150°C
Storage Temperature Range	-65°C to +150°C
Lead Temperature (Soldering, 10s)	+260°C
ESD Susceptibility	
HBM	2000V
MM	200V
CDM	1000V

## RECOMMENDED OPERATING CONDITIONS

Supply Voltage Range	3.6V to 36V
Operating Temperature Range	-40°C to +125°C

## OVERSTRESS CAUTION

Stresses beyond those listed in Absolute Maximum Ratings may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect reliability. Functional operation of the device at any conditions beyond those indicated in the Recommended Operating Conditions section is not implied.

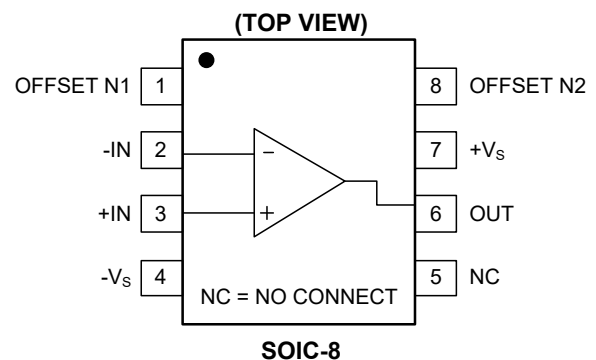
## ESD SENSITIVITY CAUTION

This integrated circuit can be damaged if ESD protections are not considered carefully. SGMICRO recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage. ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because even small parametric changes could cause the device not to meet the published specifications.

## DISCLAIMER

SG Micro Corp reserves the right to make any change in circuit design, or specifications without prior notice.

## PIN CONFIGURATION



## ELECTRICAL CHARACTERISTICS

( $V_S = \pm 5V$  to  $V_S = \pm 15V$ ,  $V_{CM} = 0V$ ,  $V_{OUT} = 0V$  and  $R_L$  connected to  $0V$ , Full =  $-40^\circ C$  to  $+125^\circ C$ , typical values are at  $T_A = +25^\circ C$ , unless otherwise noted.)

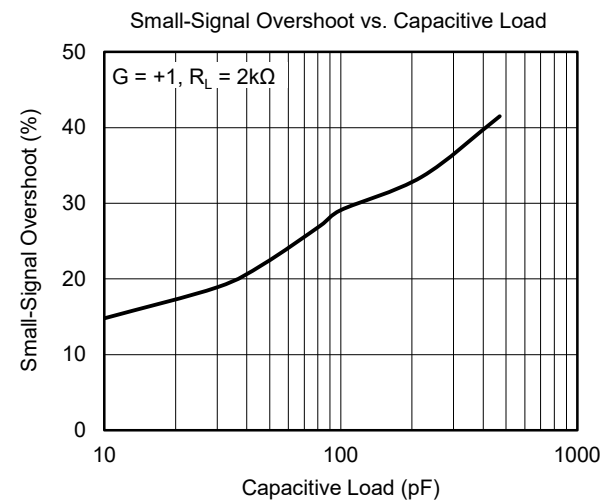
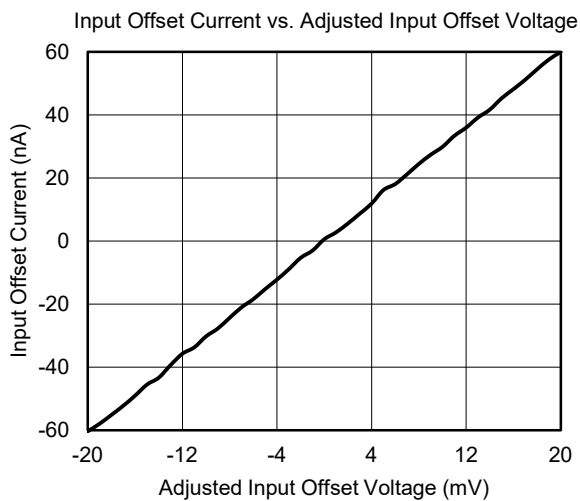
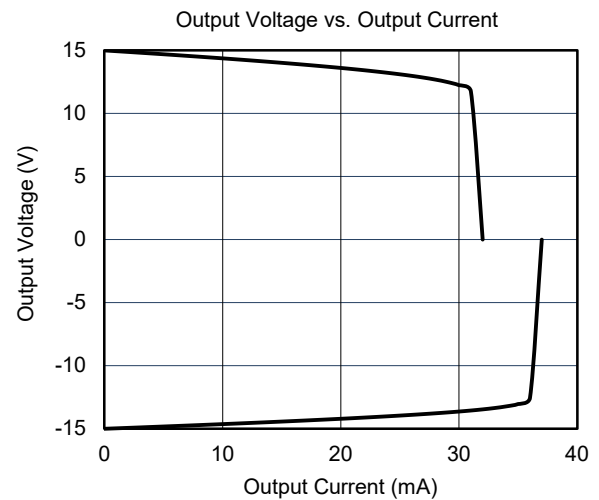
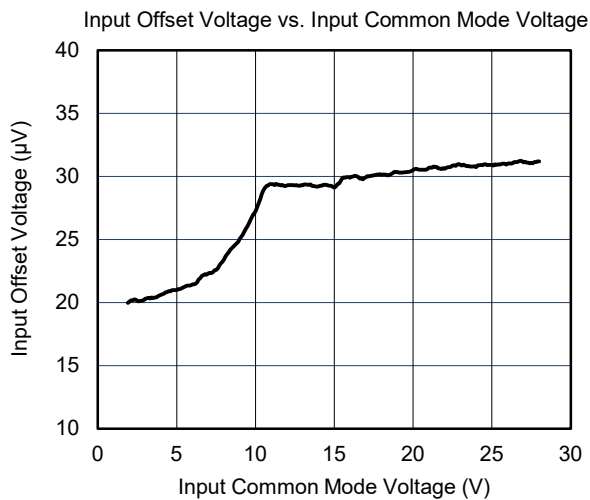
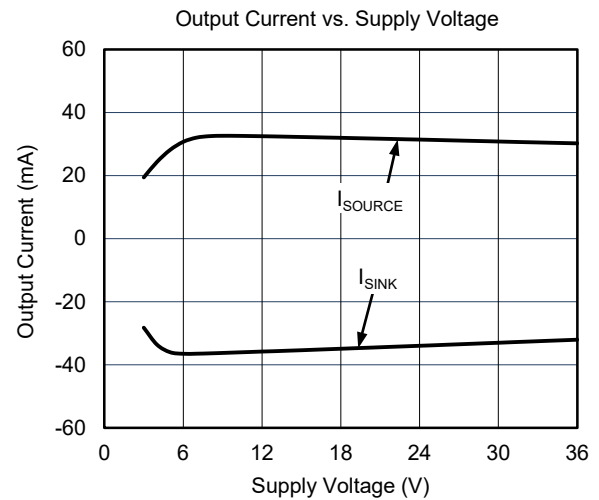
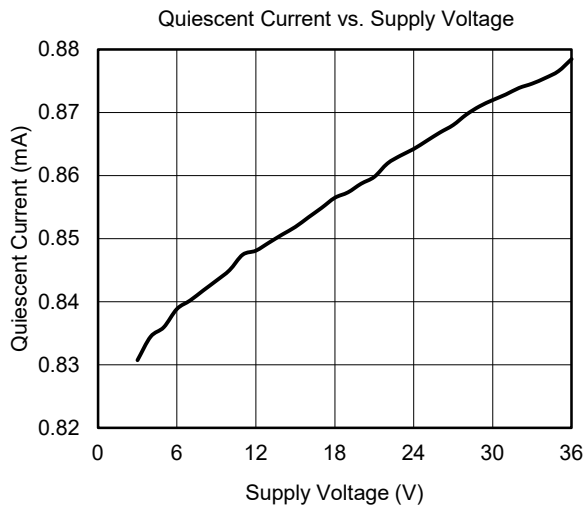
PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS
<b>Input Characteristics</b>							
Input Offset Voltage	$V_{OS}$		$+25^\circ C$		100	170	$\mu V$
			Full			290	
Input Bias Current	$I_B$	$V_{CM} = V_S/2$	$+25^\circ C$		$\pm 1$	$\pm 16$	nA
			Full			$\pm 55$	
Input Offset Current	$I_{OS}$	$V_{CM} = V_S/2$	$+25^\circ C$		$\pm 1$	$\pm 18$	nA
			Full			$\pm 28$	
Input Common Mode Voltage Range	$V_{CM}$		Full	$(-V_S) + 1.5$		$(+V_S) - 2$	V
Common Mode Rejection Ratio	CMRR	$(-V_S) + 1.5V \leq V_{CM} \leq (+V_S) - 2V$	$+25^\circ C$	115	140		dB
			Full	113			
Open-Loop Voltage Gain	$A_{OL}$	$V_S = \pm 5V$ , $V_{OUT} = \pm 2.5V$ , $R_L = 10k\Omega$	$+25^\circ C$	112	135		dB
			Full	110			
		$V_S = \pm 15V$ , $V_{OUT} = \pm 10V$ , $R_L = 10k\Omega$	$+25^\circ C$	115	126		
			Full	109			
		$V_S = \pm 5V$ , $V_{OUT} = \pm 2.5V$ , $R_L = 2k\Omega$	$+25^\circ C$	105	112		
			Full	94			
		$V_S = \pm 15V$ , $V_{OUT} = \pm 10V$ , $R_L = 2k\Omega$	$+25^\circ C$	112	120		
			Full	102			
Input Offset Voltage Drift	$\Delta V_{OS}/\Delta T$		Full		0.5		$\mu V/^\circ C$
<b>Offset Adjustment</b>							
Offset Adjustment Range		$R_S = 50k\Omega$ , See Figure 1	$+25^\circ C$		$\pm 20$		mV
External Resistance between OFFSET N1 and $+V_S$			$+25^\circ C$	15			k $\Omega$
External Resistance between OFFSET N2 and $+V_S$			$+25^\circ C$	15			k $\Omega$
<b>Output Characteristics</b>							
Output Voltage Swing from Rail	$V_{OUT}$	$V_S = \pm 15V$ , $R_L = 10k\Omega$	$+25^\circ C$		90	175	mV
			Full			220	
		$V_S = \pm 15V$ , $R_L = 2k\Omega$	$+25^\circ C$		450	850	
			Full			1060	
Output Short-Circuit Current	$I_{SC}$		$+25^\circ C$	$\pm 13$	$\pm 32$		mA
<b>Power Supply</b>							
Operating Voltage Range	$V_S$		Full	3.6		36	V
Quiescent Current/Amplifier	$I_Q$	$I_{OUT} = 0mA$	$+25^\circ C$		0.9	1.2	mA
			Full			1.3	
Power Supply Rejection Ratio	PSRR	$V_S = 3V$ to $38V$	$+25^\circ C$	121	146		dB
			Full	118			

**ELECTRICAL CHARACTERISTICS (continued)**

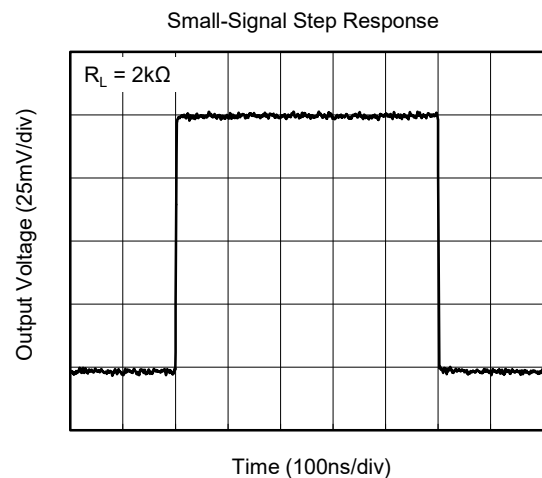
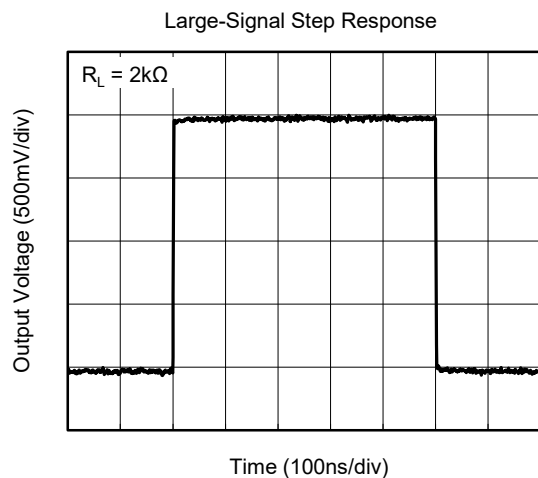
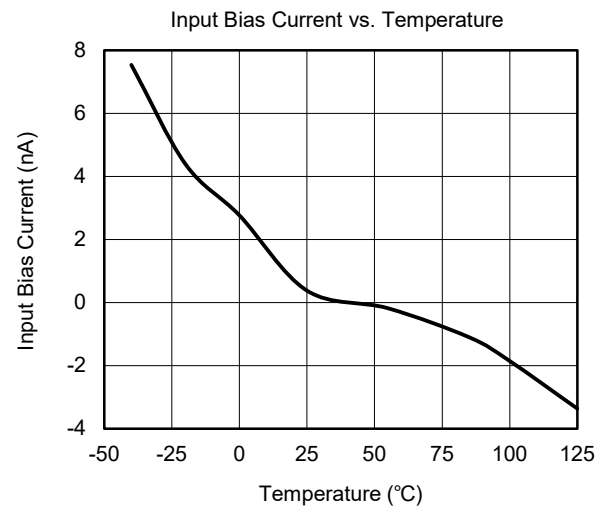
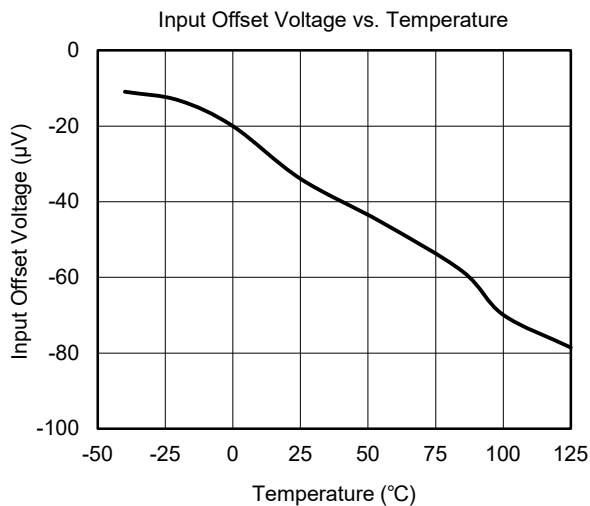
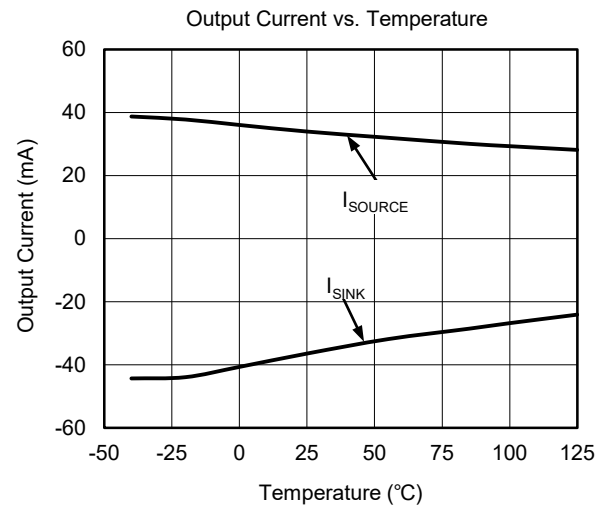
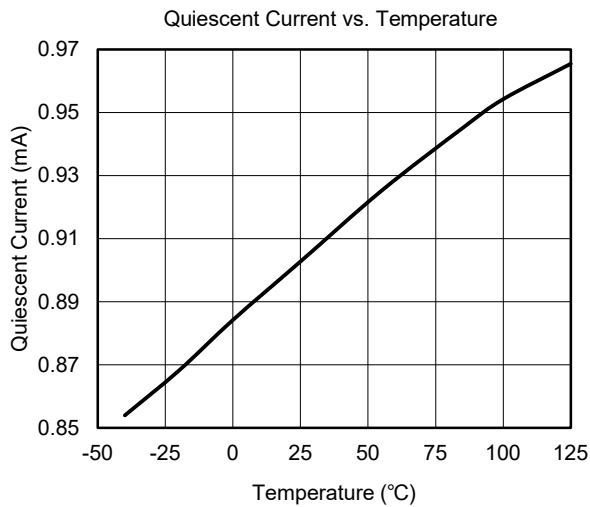
( $V_S = \pm 5V$  to  $V_S = \pm 15V$ ,  $V_{CM} = 0V$ ,  $V_{OUT} = 0V$  and  $R_L$  connected to  $0V$ , Full =  $-40^\circ C$  to  $+125^\circ C$ , typical values are at  $T_A = +25^\circ C$ , unless otherwise noted.)

PARAMETER	SYMBOL	CONDITIONS	TEMP	MIN	TYP	MAX	UNITS
<b>Dynamic Performance</b>							
Gain-Bandwidth Product	GBP	$V_{OUT} = 100mV_{P-P}$ , $R_L = 2k\Omega$ , $C_L = 10pF$	$+25^\circ C$		3		MHz
Slew Rate	SR	$R_L = 2k\Omega$	$+25^\circ C$		4		V/ $\mu s$
Settling Time to 0.1%	$t_S$	$V_{IN} = 1V$ Step, $R_L = 2k\Omega$ , $G = +1$	$+25^\circ C$		0.5		$\mu s$
Overload Recovery Time		$R_L = 2k\Omega$ , $V_{IN} \times G = V_S$	$+25^\circ C$		10		$\mu s$
Phase Margin	$\phi_O$	$V_{OUT} = 100mV_{P-P}$ , $R_L = 2k\Omega$ , $C_L = 10pF$	$+25^\circ C$		55		°
Total Harmonic Distortion + Noise	THD+N	$V_{IN} = 1V_{RMS}$ , $G = +1$ , $R_L = 2k\Omega$ , $f = 1kHz$	$+25^\circ C$		0.0008		%
<b>Noise</b>							
Input Voltage Noise		$f = 0.1Hz$ to $10Hz$	$+25^\circ C$		300		$nV_{P-P}$
Input Voltage Noise Density	$e_n$	$f = 1kHz$	$+25^\circ C$		8.5		$nV/\sqrt{Hz}$
Input Current Noise Density	$i_n$	$f = 1kHz$	$+25^\circ C$		1.5		$pA/\sqrt{Hz}$

## TYPICAL PERFORMANCE CHARACTERISTICS

At  $T_A = +25^\circ\text{C}$  and  $V_S = \pm 15\text{V}$ , unless otherwise noted.

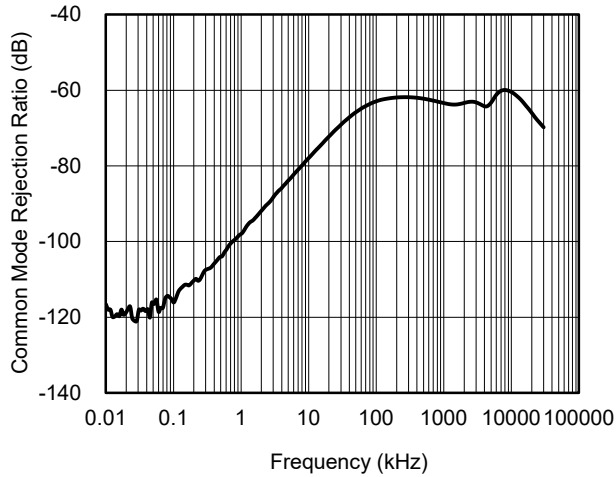
## TYPICAL PERFORMANCE CHARACTERISTICS (continued)

At  $T_A = +25^\circ\text{C}$  and  $V_S = \pm 15\text{V}$ , unless otherwise noted.

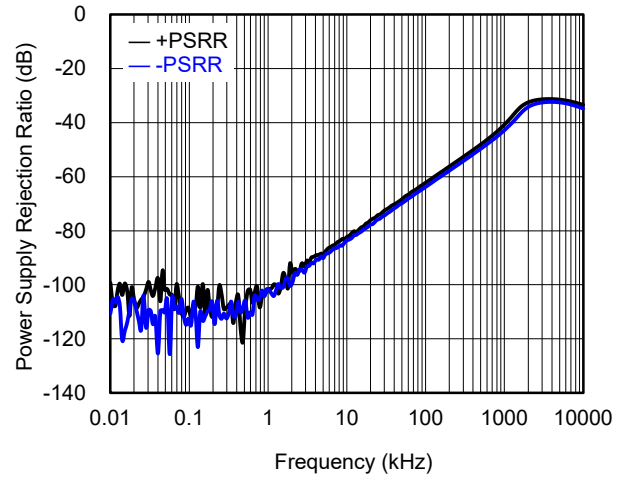
## TYPICAL PERFORMANCE CHARACTERISTICS (continued)

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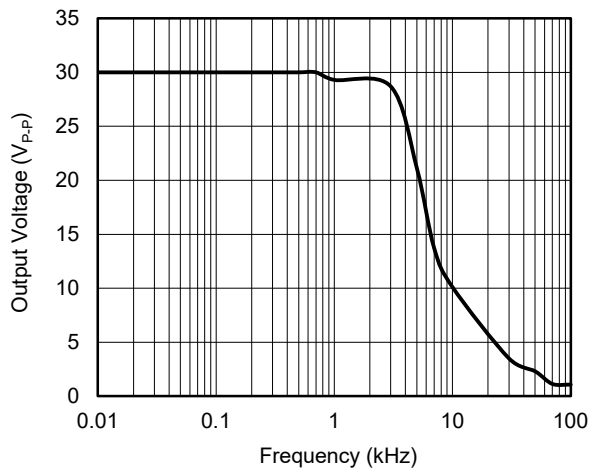
CMRR vs. Frequency



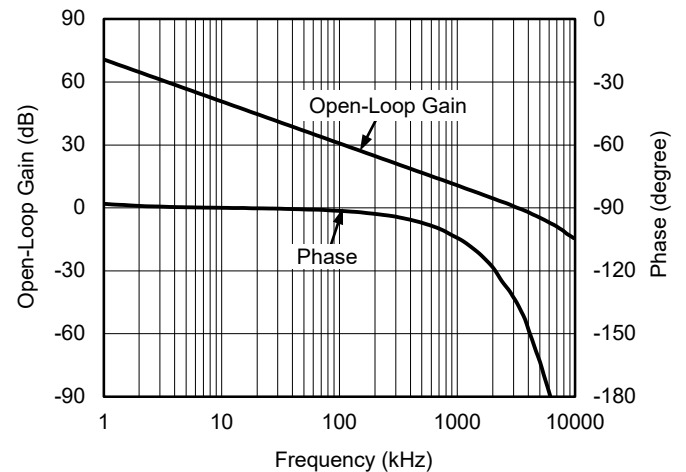
PSRR vs. Frequency



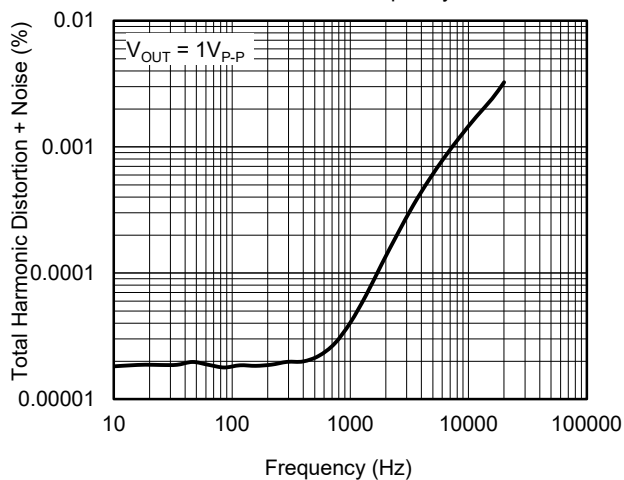
Maximum Output Voltage vs. Frequency



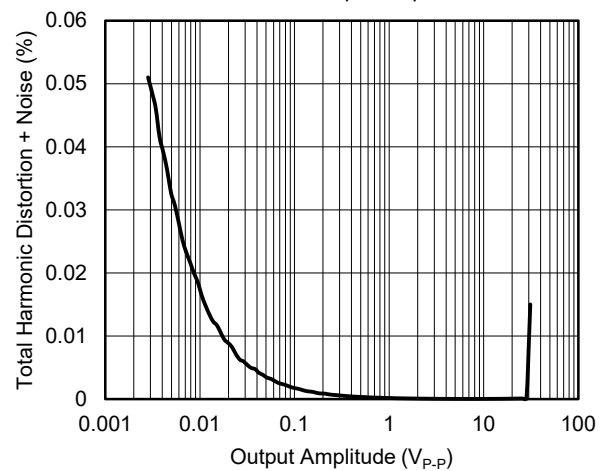
Open-Loop Gain and Phase vs. Frequency



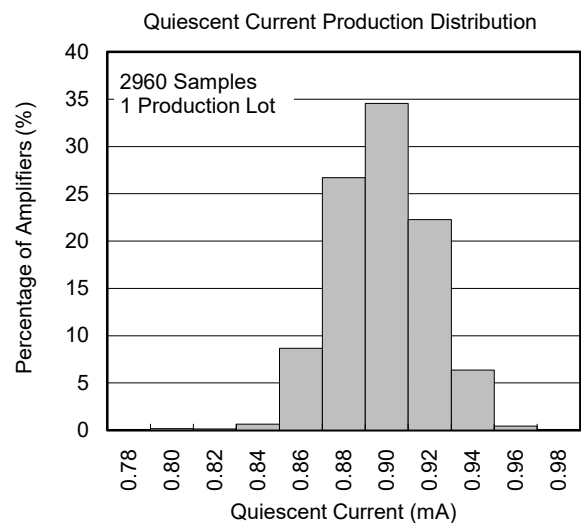
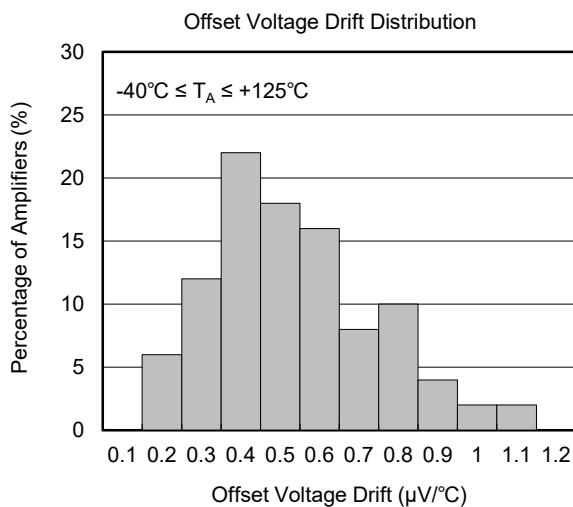
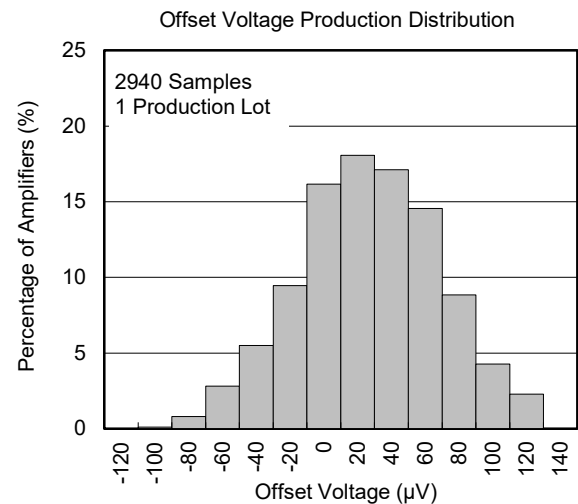
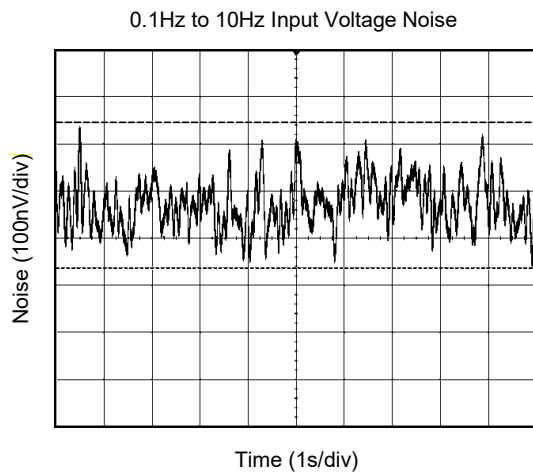
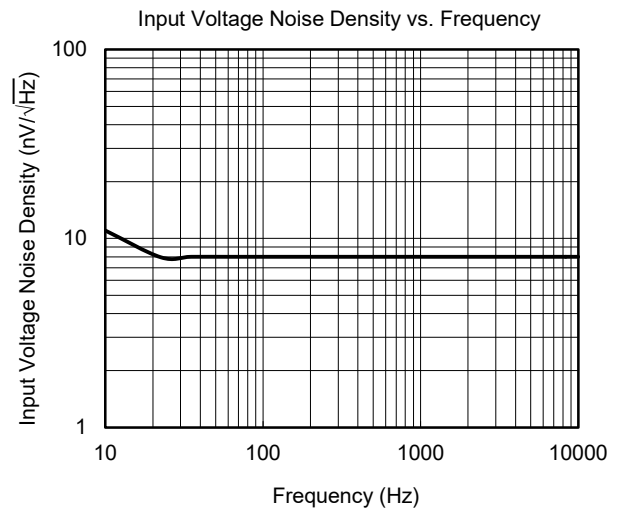
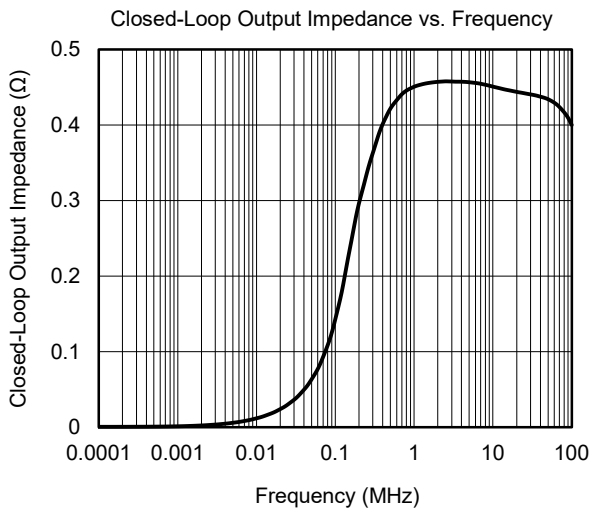
THD+N vs. Frequency



THD+N vs. Output Amplitude



## TYPICAL PERFORMANCE CHARACTERISTICS (continued)

At  $T_A = +25^\circ\text{C}$  and  $V_S = \pm 15\text{V}$ , unless otherwise noted.



## APPLICATION INFORMATION

## General Application

The input offset voltage comes from an internal mismatch in the input stage. Mismatched transistor pairs, current gain ( $\beta$ ), collector currents, emitter or collector resistors result in mismatches in the differential input stages of the operational amplifier. As shown in Figure 1, it is recommended to adjust these mismatches through an external circuit by placing resistors between the inputs. Or, a potentiometer placed between inputs is recommended as well, which is appropriate for trimming the circuit in test and applications requiring precision control of offset. It is important to ensure that the resistance between OFFSET N1 and  $+V_S$  and the resistance between OFFSET N2 and  $+V_S$  are not less than 15k $\Omega$ .

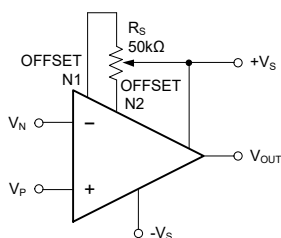


Figure 1. Input Offset Voltage Null Circuit

## Power Supply Decoupling and Layout

A clean and low noise power supply is very important in amplifier circuit design, besides of input signal noise, the power supply is one of important source of noise to the amplifier through  $+V_S$  and  $-V_S$  pins. Power supply bypassing is an effective method to clear up the noise at power supply, and the low impedance path to ground of decoupling capacitor will bypass the noise to GND. In application, 10 $\mu$ F ceramic capacitor paralleled with 0.1 $\mu$ F or 0.01 $\mu$ F ceramic capacitor is used in Figure 1. The ceramic capacitors should be placed as close as possible to  $+V_S$  and  $-V_S$  power supply pins.

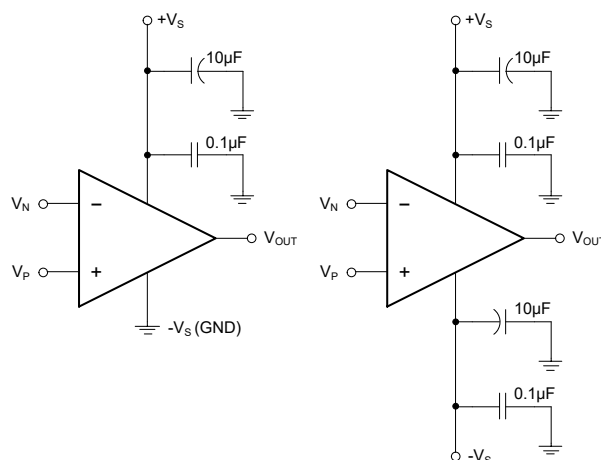


Figure 2. Amplifier Power Supply Bypassing

## Grounding

In low speed application, one node grounding technique is the simplest and most effective method to eliminate the noise generated by grounding. In high speed application, the general method to eliminate noise is to use a complete ground plane technique, and the whole ground plane will help distribute heat and reduce EMI noise pickup.

## Reduce Input-to-Output Coupling

To reduce the input-to-output coupling, the input traces must be placed as far away from the power supply or output traces as possible. The sensitive trace must not be placed in parallel with the noisy trace in same layer. They must be placed perpendicularly in different layers to reduce the crosstalk. These PCB layout techniques will help to reduce unwanted positive feedback and noise.

## APPLICATION INFORMATION (continued)

## Typical Application Circuits

## Difference Amplifier

The circuit in Figure 3 is a design example of classical difference amplifier. If  $R_4/R_3 = R_2/R_1$ , then  $V_{OUT} = (V_P - V_N) \times R_2/R_1 + V_{REF}$ .

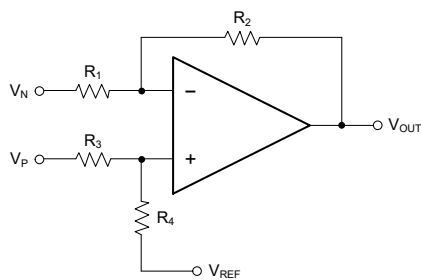


Figure 3. Difference Amplifier

## High Input Impedance Difference Amplifier

The circuit in Figure 4 is a design example of high input impedance difference amplifier, the added amplifiers at the input are used to increase the input impedance and eliminate drawback of low input impedance in Figure 3.

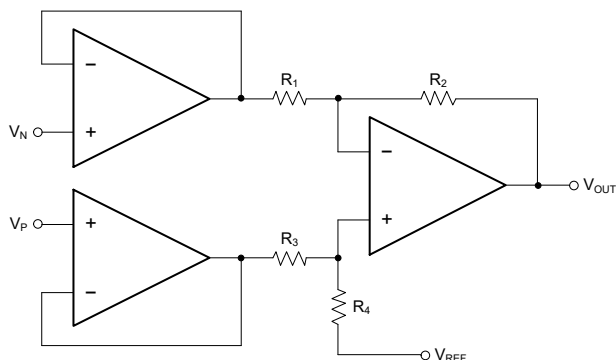


Figure 4. High Input Impedance Difference Amplifier

## Active Low-Pass Filter

The circuit in Figure 5 is a design example of active low-pass filter, the DC gain is equal to  $-R_2/R_1$  and the -3dB corner frequency is equal to  $1/2\pi R_2 C$ . In this design, the filter bandwidth must be less than the bandwidth of the amplifier, the resistor values must be selected as low as possible to reduce ringing or oscillation generated by the parasitic parameters in PCB layout.

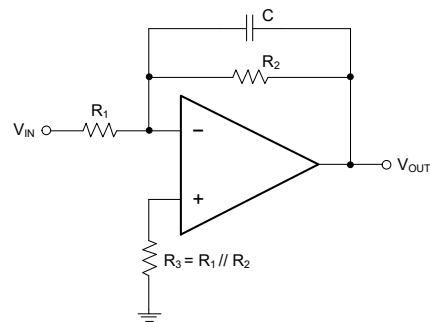


Figure 5. Active Low-Pass Filter

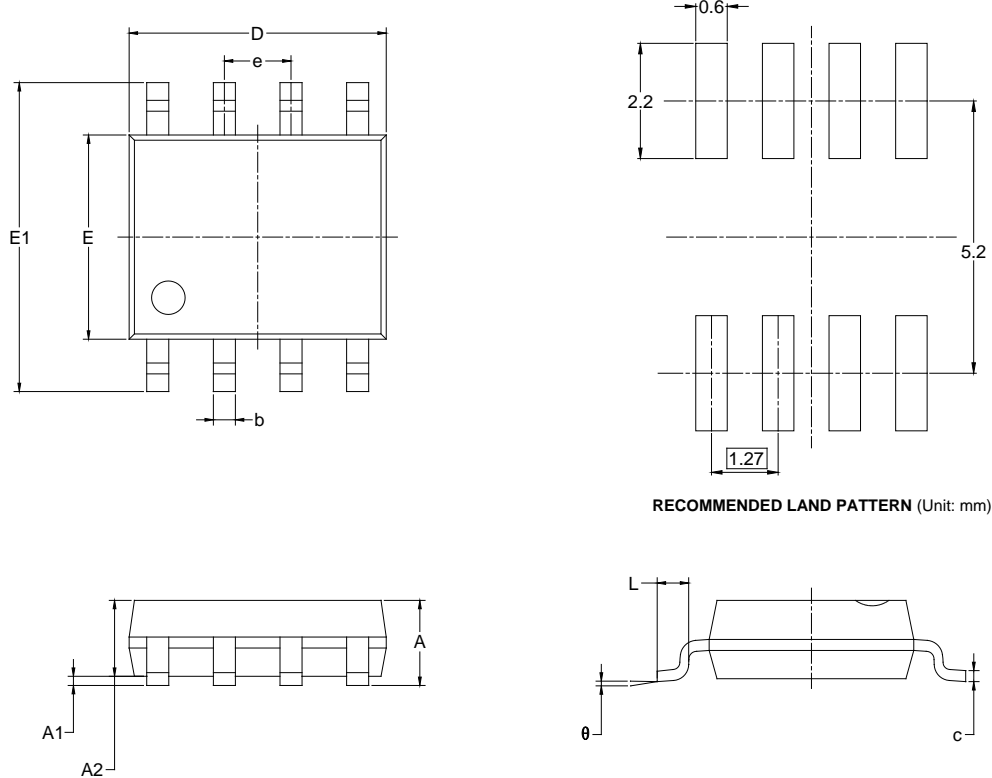
## REVISION HISTORY

NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

MARCH 2023 – REV.A.1 to REV.A.2		Page
Updated Typical Performance Characteristics section .....		7
AUGUST 2017 – REV.A to REV.A.1		Page
Added external resistance parameter .....		3
Updated open-loop gain and phase vs. frequency .....		7
Changes from Original (AUGUST 2017) to REV.A		Page
Changed from product preview to production data .....		All

## PACKAGE OUTLINE DIMENSIONS

### SOIC-8



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MIN	MAX	MIN	MAX
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.27 BSC		0.050 BSC	
L	0.400	1.270	0.016	0.050
$\theta$	0°	8°	0°	8°

#### NOTES:

1. Body dimensions do not include mold flash or protrusion.
2. This drawing is subject to change without notice.

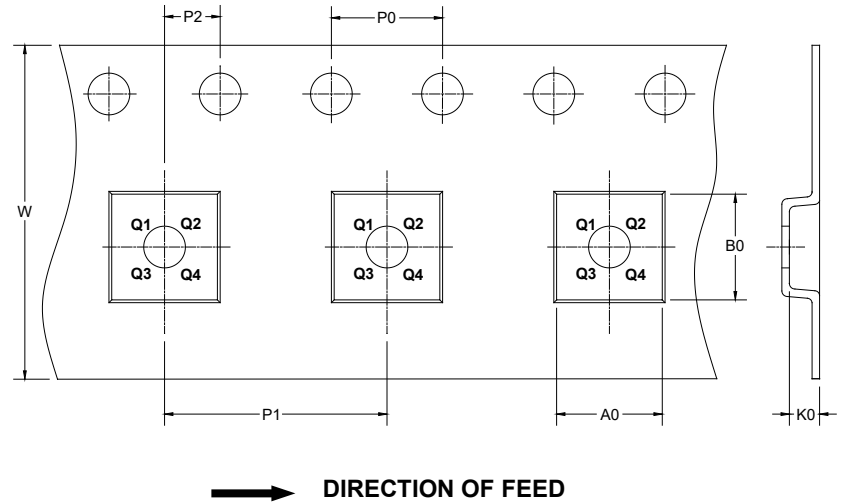
# PACKAGE INFORMATION

## TAPE AND REEL INFORMATION

### REEL DIMENSIONS



### TAPE DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

### KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SOIC-8	13"	12.4	6.40	5.40	2.10	4.0	8.0	2.0	12.0	Q1

DD00001

## PACKAGE INFORMATION

### CARTON BOX DIMENSIONS



NOTE: The picture is only for reference. Please make the object as the standard.

### KEY PARAMETER LIST OF CARTON BOX

Reel Type	Length (mm)	Width (mm)	Height (mm)	Pizza/Carton
13"	386	280	370	5

DD0002